

AN11258

I2C secondary boot loader

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Application note

Document information

Info	Content
Keywords	LPC11xx, LPC17xx, SBL, I2C
Abstract	This application note describes how to implement a Secondary Boot Loader (SBL) using I2C Communication.



Revision history

Rev	Date	Description
1	20120912	Initial version.

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1. Introduction

This document describes functional requirement specifications, implementation and usage of the I2C Secondary Boot Loader (SBL) on NXP's LPC11xx and LPC17xx family.

1.1 Project overview

This project can run on LPC11xx and LPC17xx MCUs. In these MCUs, the primary boot loader resides in the boot block. The primary boot loader is executed every time the part is powered on or reset. It can execute the ISP command handler or the user application code which is stored in sectors of internal flash memory.

The SBL in this project refers to a user-defined application that provides the user with an option to update the user application firmware or execute the previously programmed user application firmware. It is placed from address 0x00 so that when the primary boot loader runs user application, it executes first.

1.2 System components

The system components are shown in [Fig 1](#).

UART communication between the PC and the master MCU is added to give user control over the firmware upgrade process.

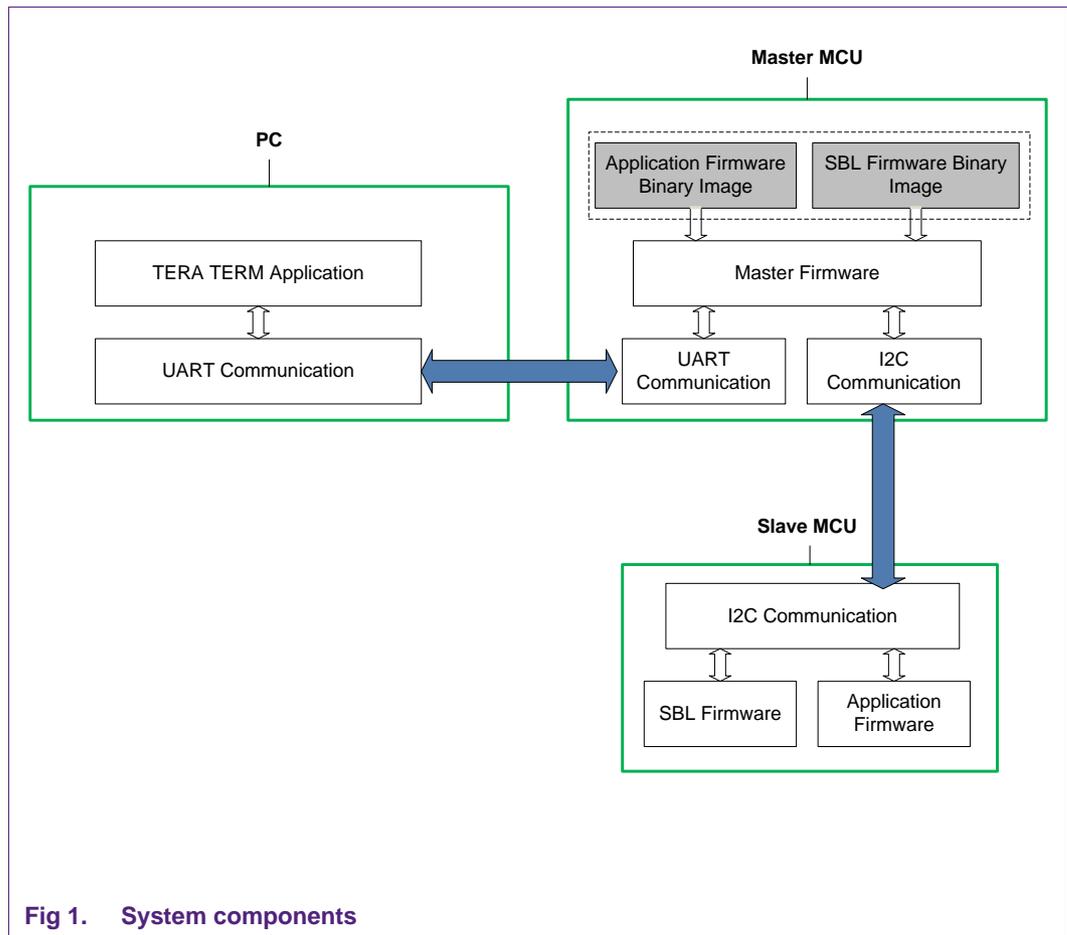


Fig 1. System components

The user interacts with master MCU using Tera Term. The master MCU supports three commands: Read user application firmware ID of slave MCU, Upgrade user application firmware, and Upgrade SBL firmware for slave MCU. Firmware data (user application firmware and SBL firmware) is stored in flash memory of master MCU, from the sector 1 to the last sector.

Once the master MCU receives a command, it communicates to the slave MCU to perform the relevant actions. All transmissions between master MCU and the slave MCU are done using I2C. The protocol in this case is covered in the section 3.

Slave MCU has an SBL located at the first sector of flash memory. At startup, SBL validates user code by checking the firmware version ID (the last 4 bytes of flash memory). If the ID is invalid (0xFFFFFFFF), the slave MCU enters SBL mode and waits for new firmware over I²C-bus. If not, the MCU enters Application mode and executes the Reset Handler of user application firmware at address 0x1004.

In Application Mode, the slave still supports functions to read its user application firmware version ID and upgrade the user application firmware. Moreover, the firmware of SBL can also be upgraded. Using a special command, the user can ask the master MCU to communicate to the slave MCU in order to perform this function.

1.3 I2C communication

A typical I²C-bus configuration is shown in Fig 2. Depending on the state of the direction bit (R/W), two types of data transfers are possible on the I²C-bus:

- Data transfer from a master transmitter to a slave receiver. The first byte transmitted by the master is the slave address. Next follows a number of data bytes. The slave returns an acknowledge bit after each received byte.
- Data transfer from a slave transmitter to a master receiver. The first byte (the slave address) is transmitted by the master. The slave then returns an acknowledge bit. Next follows the data bytes transmitted by the slave to the master. The master returns an acknowledge bit after all received bytes other than the last byte. At the end of the last received byte, a “not acknowledge” is returned.

The master device generates all of the serial clock pulses and the START / STOP conditions. A transfer is ended with a STOP condition or with a Repeated START condition. Since a Repeated START condition is also the beginning of the next serial transfer, the I²C-bus will not be released.

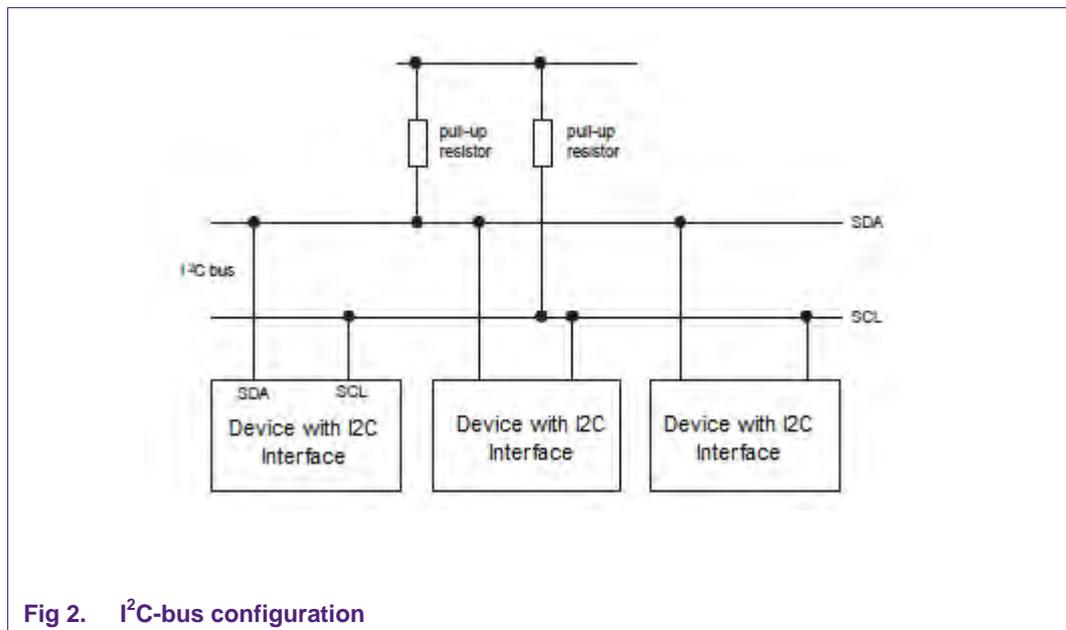


Fig 2. I²C-bus configuration

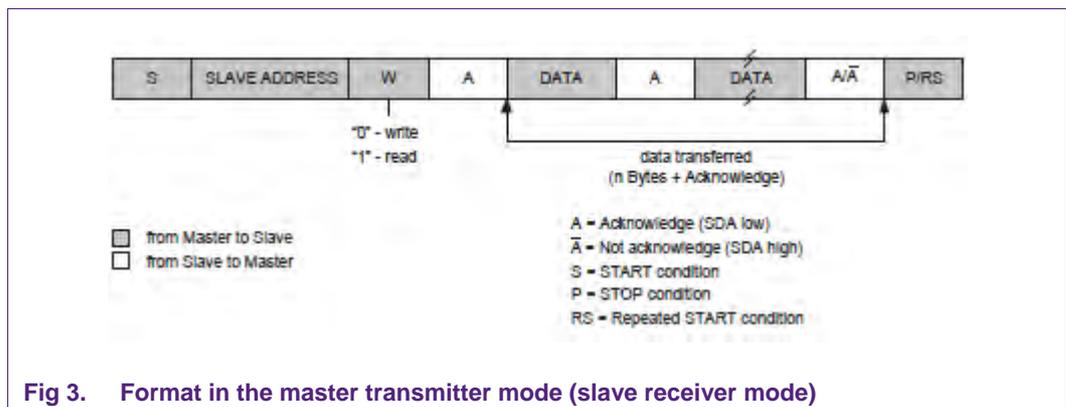
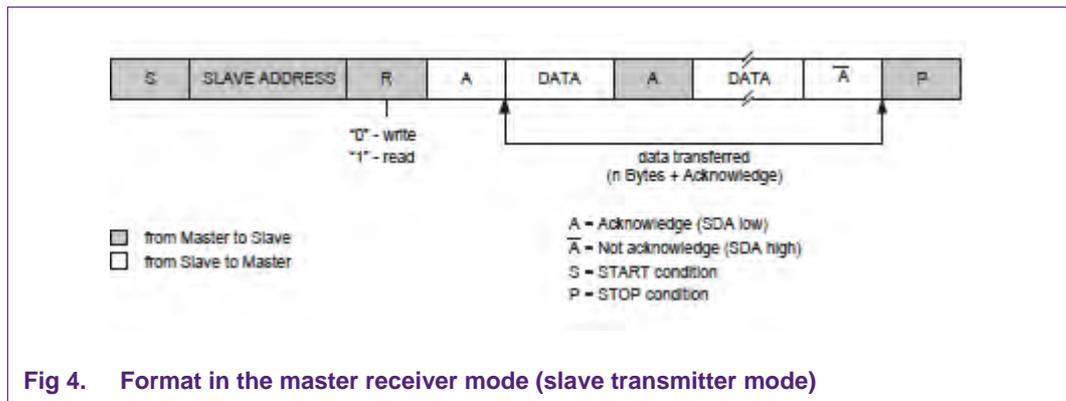


Fig 3. Format in the master transmitter mode (slave receiver mode)



2. System overview

2.1 Project configuration

I2C configuration:

I2C slave Address: 0x60

I2C Clock rate: 1 MHz

UART configuration:

Baud rate: 115200

Data: 8 bits

Stop bits: 1

Parity bit: None

Flow Control: None

2.2 Memory map

2.2.1 Memory map for SBL master MCU

The master's firmware resides on sector 0 of its internal flash memory. The remaining sectors are reserved to store firmware data. When the master MCU has to upgrade SBL firmware or user application firmware, it reads data from these sectors.

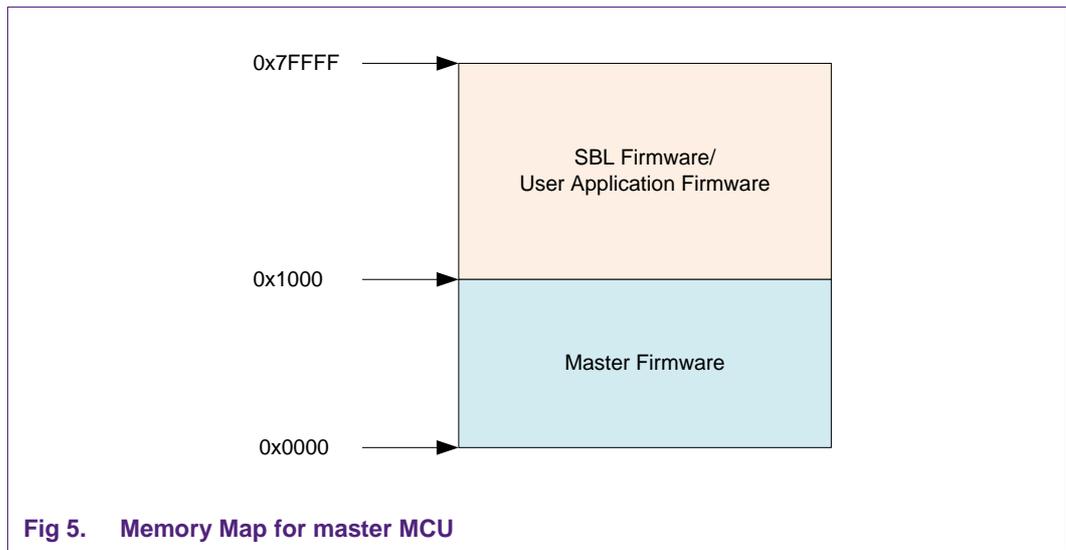


Fig 5. Memory Map for master MCU

2.2.2 Memory map for SBL slave MCU

The flash memory is divided into two regions. One region is for the placement of the user application firmware and the other region is for the placement of SBL. The SBL is placed at the first 4 kB of flash memory and runs first when the system resets.

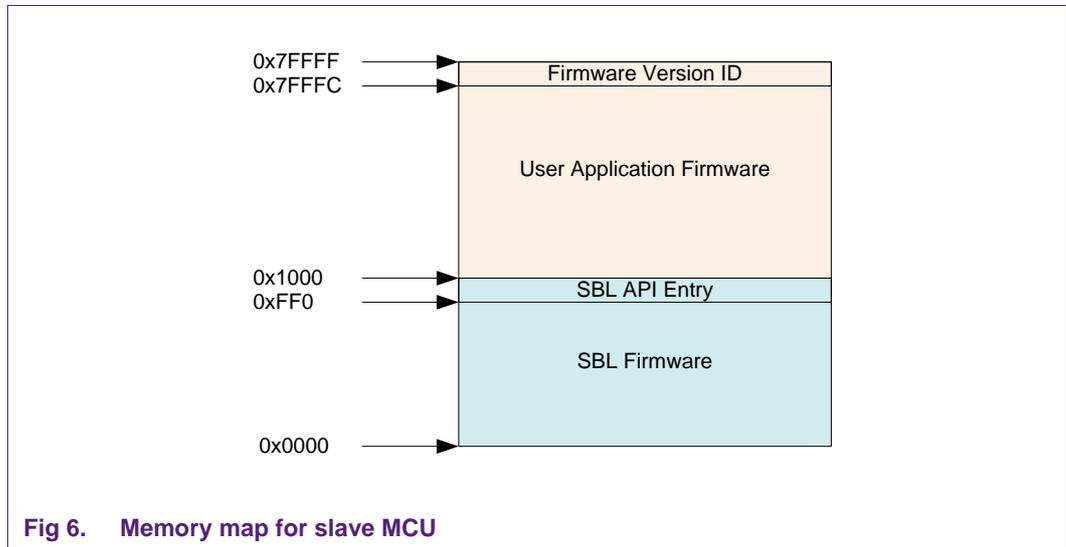


Fig 6. Memory map for slave MCU

As in [Fig 6](#), the Firmware Version ID is stored in the last 4 bytes of flash memory, from 0x7FFFC if LPC17xx MCU is used as slave MCU and 0x7FFC if LPC11xx MCU is used as slave MCU. The SBL also provides an entry point for calling SBL APIs. The address of the entry is from 0xFF0.

3. Functional description

3.1 SBL mode

3.1.1 Read firmware version ID

Function ID: 0x31

Description:

- This function allows the SBL master MCU to read the user application firmware version ID from SBL slave MCU.

Implementation:

- The SBL master waits for a READY byte (0xAA) over I2C.
- The SBL master makes a request to read the user application firmware version ID by issuing a function ID to the SBL slave.
- Upon receiving the request, the SBL slave will prepare the user application firmware version ID information.
- The SBL master will then retrieve the aforesaid firmware version ID information by issuing an SBL read instruction.

Communication protocol:

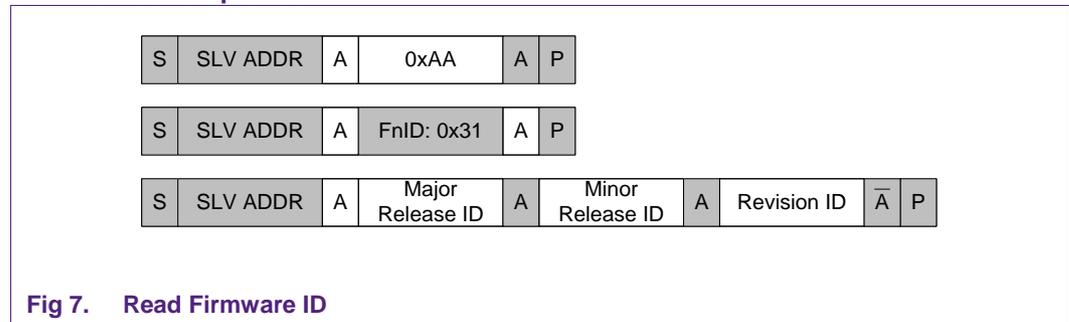


Fig 7. Read Firmware ID

Major release ID:

- Range of ID: 0 - 255

Minor release ID:

- Range of ID: 0 - 255

Revision ID:

- Range of ID: 0, a-f

3.1.2 User application firmware upgrade

Function ID: 0x32

Description:

- This function performs programming of the flash memory by the application program in a running system with an aim to upgrade the user application firmware.

Implementation:

- The SBL master waits for a READY byte (0xAA) over I2C.
- The SBL master makes a request to enter IAP mode by issuing a function ID to the SBL slave.

- The SBL slave erases the last sector of flash memory, which stores the Firmware Version ID information. Then it enters to IAP mode.
- The SBL master transfers firmware data to the SBL slave one block at a time via I2C. Each block of data is 1 kB in size.
- The SBL slave programs the flash one block at a time. The flash on the SBL slave is divided into sectors. Each sector has a size of 4 kB. The SBL slave will always prepare and erase the contents of a flash sector, when it receives first 1 kB block of data for every new sector.
 - Once the first block of data has been programmed, the SBL slave is ready to receive the next block of data.
 - When the second block of data is received, since the contents of entire flash sectors are already cleared, the SBL slave shall directly prepare and program the second block of data at a location that is 1 kB offset from the start of the sector.
- This process continues until the SBL master sends the last block of flash data.
- In order to inform the SBL slave that there are no more data, the SBL master would send Block num (MSB) and Block num (LSB) bytes having a value of 0x00.
- When the IAP process is completed, the SBL slave will execute Reset Handler of user application firmware at address 0x1004.

Communication protocol:

1. The SBL master follows this communication protocol to send the first 1 kB block of data.

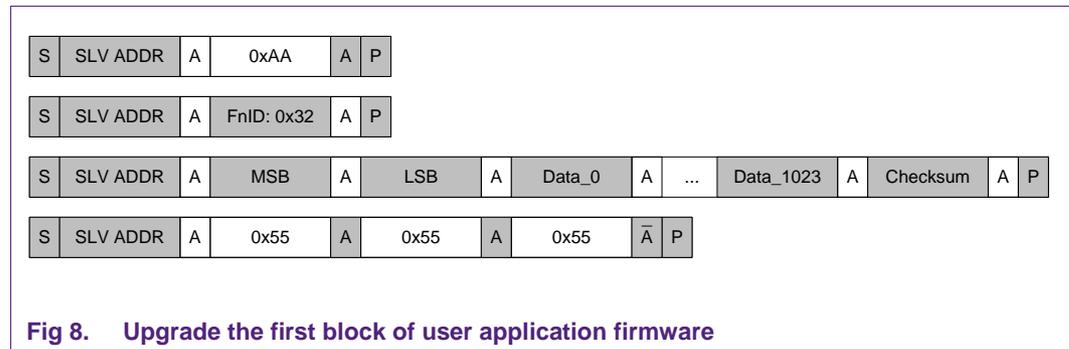


Fig 8. Upgrade the first block of user application firmware

Function ID:

- The function ID used to perform IAP is 0x32. The SBL master is required to send the function ID as the first byte so that the SBL slave can enter IAP mode.

Block num (MSB & LSB)

- Represents the block number that the SBL master is sending.
 E.g. For block number 1: Block num (MSB) – 0x00, Block num (LSB) – 0x01
 For block number 257: Block num (MSB) – 0x01, Block num (LSB) – 0x01

1024 bytes of data

- Represents the 1 kB block of data that is used for programming the flash on the SBL slave.

Checksum byte

- Checksum is used to check the integrity of the SBL transfer.

- Checksum is initialized as 0.
- Computation of Checksum:
 $Checksum = 0 - Block\ num\ (MSB) - Block\ num\ (LSB) - Data_0 - \dots - Data_1023$

When the SBL master completes the transmission of the block of data, the SBL master will read continuously the status of the Secondary Boot Loader. When 3 bytes of 0x55 are received, the SBL master understands that the SBL slave has received data successfully. If not, the SBL master will resend the block.

SBL status

- If the three SBL status bytes received are '0x55', this means that programming is successful for the 1 kB of data.
 - If the three SBL status bytes received are '0xFF', this means that there are errors during programming of the 1 kB of data.
2. The SBL master follows this communication protocol to send the second and subsequent blocks of data.

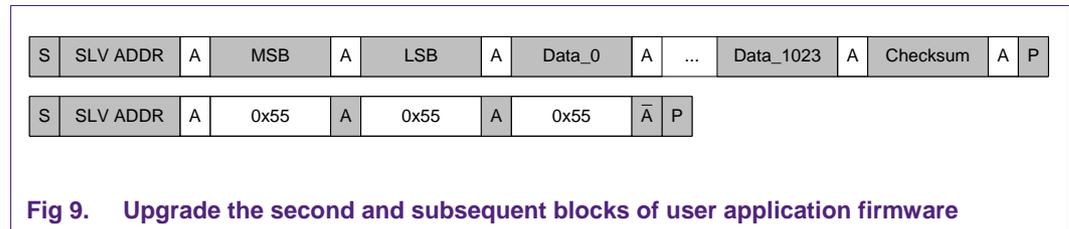


Fig 9. Upgrade the second and subsequent blocks of user application firmware

Fn ID

- The function ID is not required here since the SBL slave is now in IAP mode.
 - The absence of function ID is the only difference in the SBL communication protocol between the transmission of the first and subsequent blocks of data.
3. The SBL master follows this communication protocol to inform the SBL slave that there are no more data to send from the SBL master.

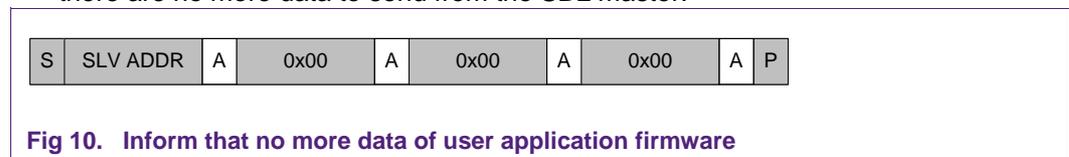


Fig 10. Inform that no more data of user application firmware

Block num (MSB) and (LSB)

- Block num (MSB): 0x00
- Block num (LSB): 0x00

Checksum byte

- Generated using Command ID, Block num (MSB) and (LSB)
- Computation: $Checksum = 0 - Block\ num\ (MSB) - Block\ num\ (LSB)$

3.1.3 SBL firmware upgrade

Function ID: 0x33

Description:

- This function performs programming of Sector 0 by the application program in a running system.

Implementation:

- The SBL master waits for a READY byte over I2C.
- The SBL master makes a request to program sector 0 of the flash memory by issuing a function ID (0x33) to the SBL slave.
- Following next, the SBL master transfers firmware data to the SBL slave one block at a time via I2C. Each block of data is 1 kB in size.
- The SBL slave will always prepare and erase the contents of a flash sector when it receives first 1kB of data.
- The SBL slave programs the flash one block at a time. (Each sector of the flash memory contains four blocks of 1kB of memory)
- After the SBL master sends the last block of flash data, it would send Block Num (MSB) and Block Num (LSB) bytes having a value of 0x00 to inform the SBL slave MCU that there are no more data.
- When the IAP process is completed, the SBL slave will reset the system.

Communication protocol:

The I2C communication protocol for programming the SBL region on flash memory is similar to the I2C communication protocol for programming the User Application region.

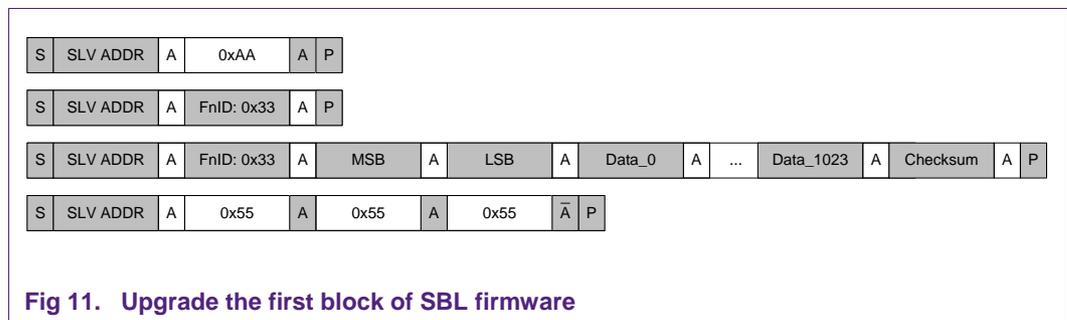


Fig 11. Upgrade the first block of SBL firmware

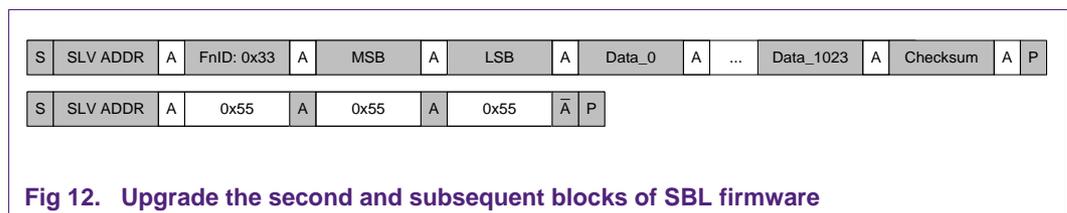


Fig 12. Upgrade the second and subsequent blocks of SBL firmware

3.2 Fail-safe implementation

The fail-safe mechanism is to ensure that in the event of loss of power during In-Application Programming, the MCU is able to re-start and complete the IAP process when the power resumes.

Implementation:

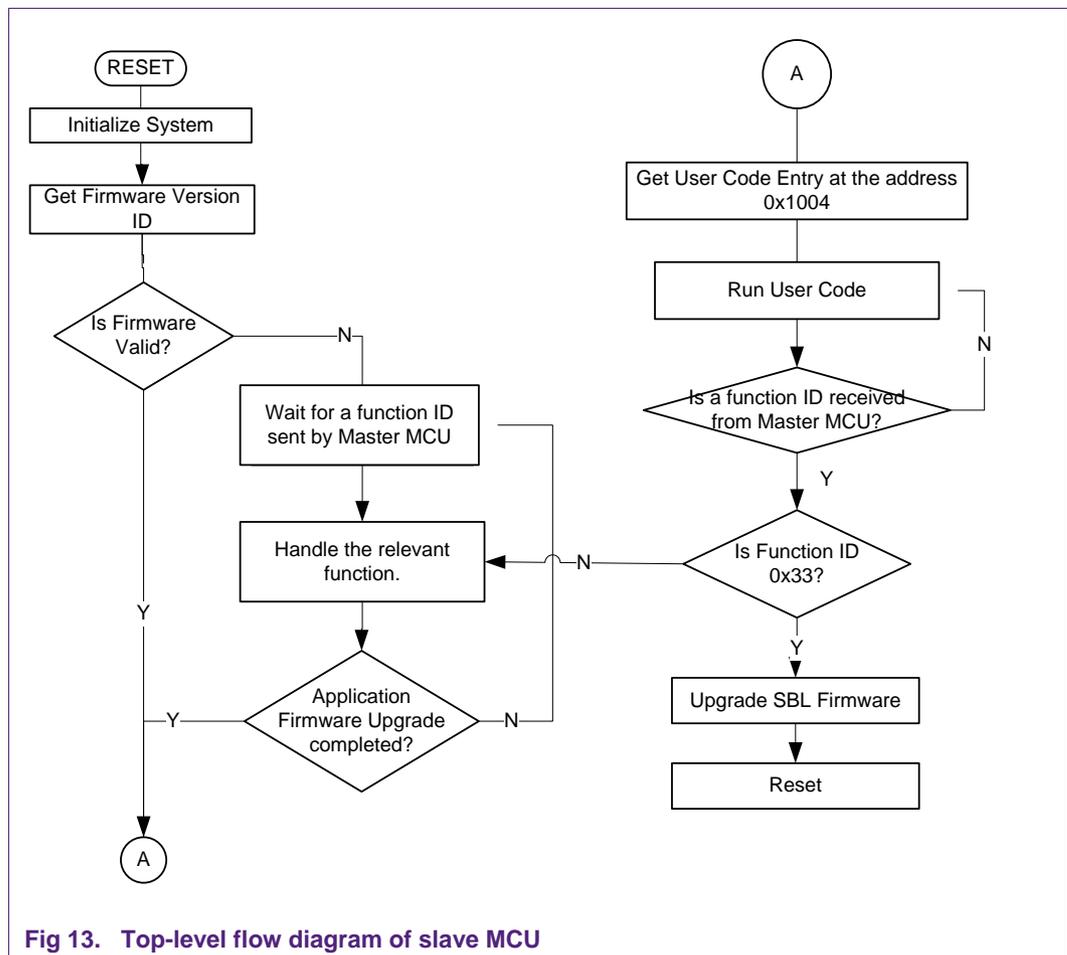
There are three important implementations in achieving the fail-safe mechanism for IAP.

1. Have a main function that decides if the flow of execution should go to the User Application or to the In-Application Programming Process.

2. Create and embed a user application firmware ID at an address located at the end of the flash memory.
 - The Firmware ID is used as a determinant to identify if the User Application Code is intact. If the check is successful, it will enter the User Application. Otherwise, it enters in IAP mode to program the user application firmware.
 - This Firmware ID is located at the end of the flash memory to ensure that this data will be the last to be programmed during IAP process. In the event when the Firmware ID is invalid (0xFFFFFFFF), this means that the User Application Code has defects. One reason for this is that the previous IAP process is not successful.
 - In the main function, the MCU will always try to enter IAP mode if the Firmware ID is not valid.
3. The first task into the IAP mode is to erase the Firmware ID the last sector to commence the IAP process.

4. Implementation

4.1 Top-level flow diagram



4.2 SBL mode

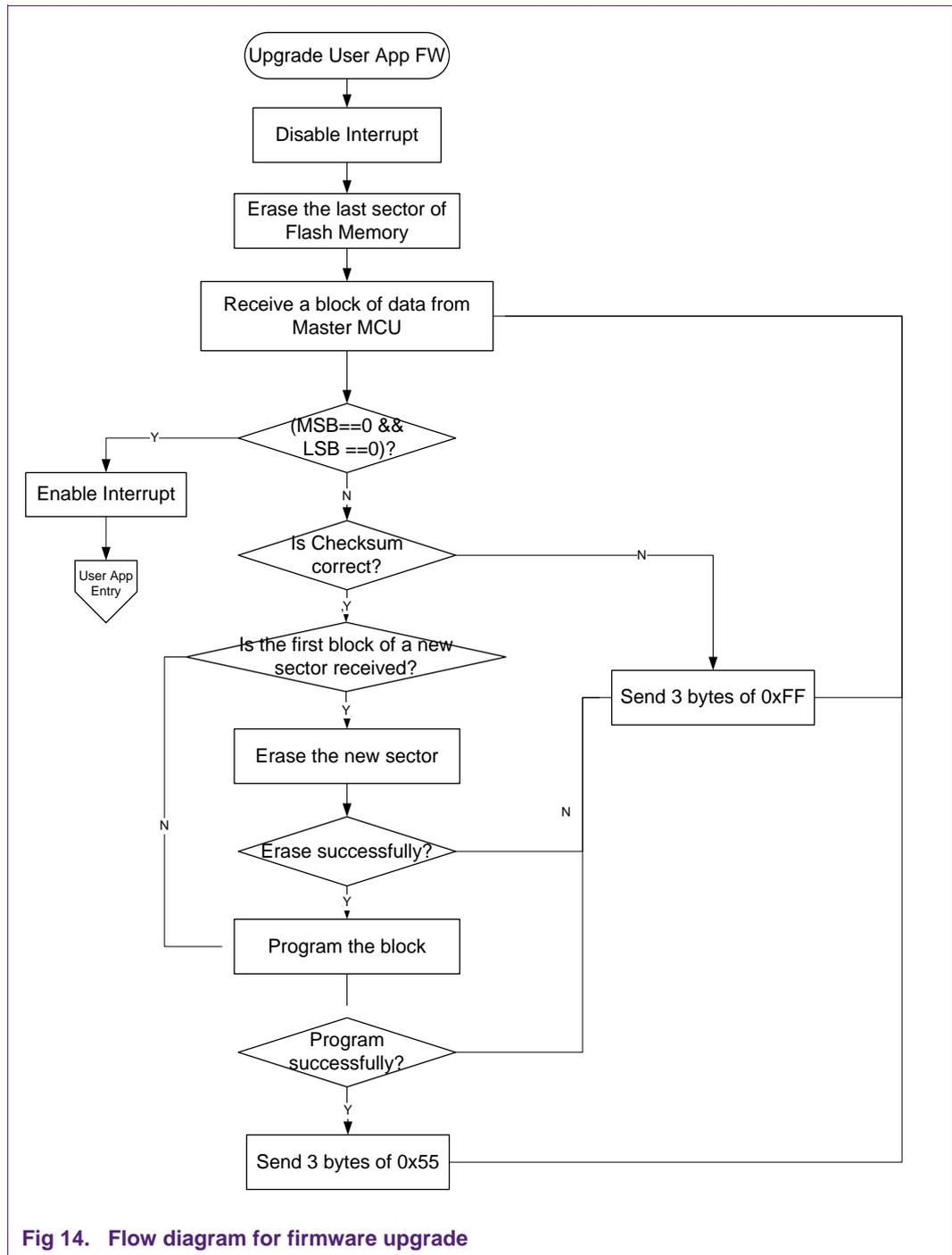
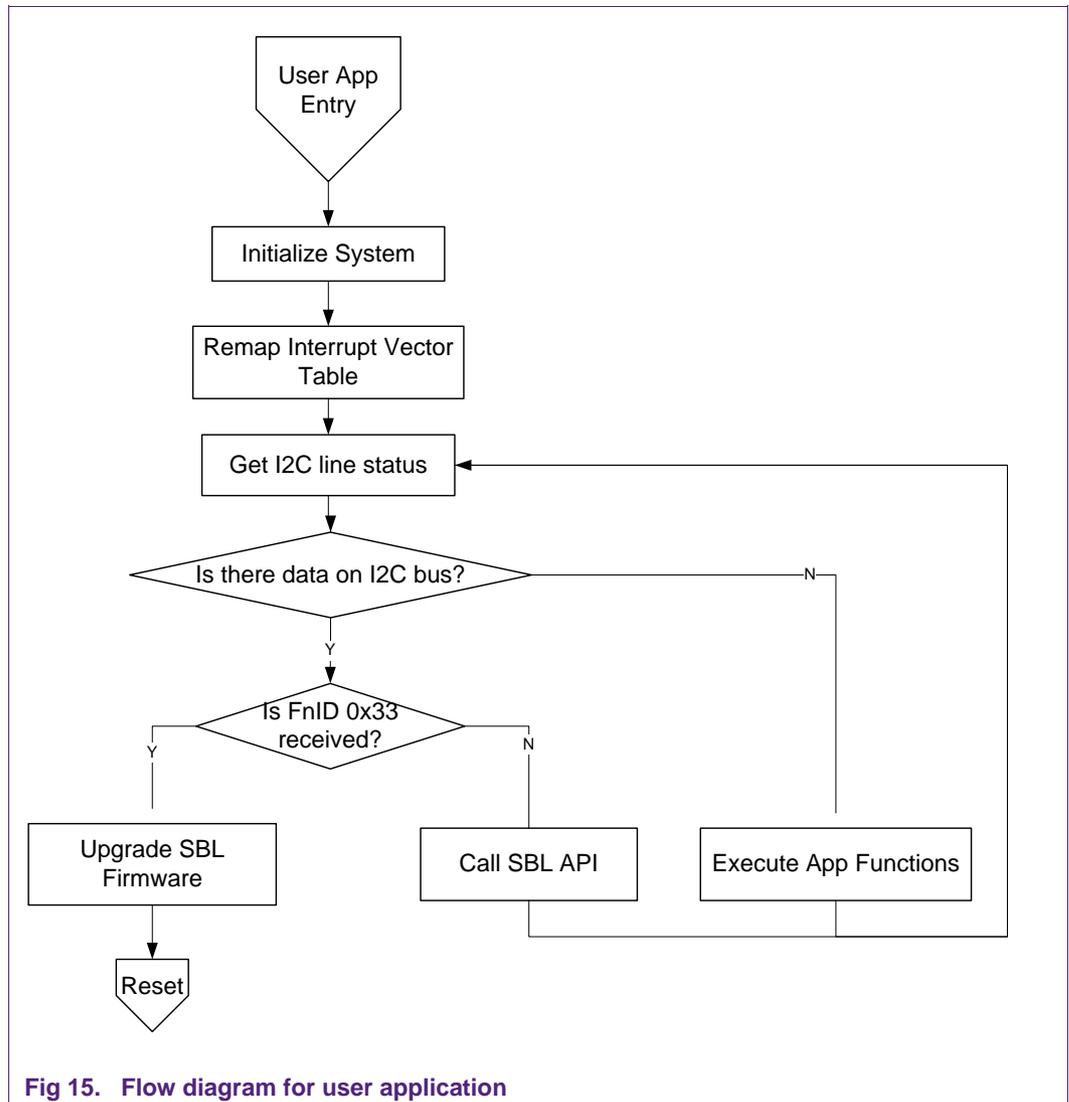


Fig 14. Flow diagram for firmware upgrade

4.3 Application mode



The SBL function could be called in the following way using C.

```

#define SBL_LOCATION 0xFF1
typedef void (*sbl_api)(uint32_t API_Code, uint8_t* pParam);
  
```

Create function pointer and call it:

```

sbl_api entry;
entry = (sbl_api) (SBL_LOCATION);
(entry)(API_Code, Params);
  
```

The parameters will be passed as shown in [Table 1](#):

Table 1. SBL APIs

API_Code	Params	Description
0x01	None	Enter SBL Mode.
0x02	None	Exit SBL Mode.
0x03	Function ID (Size = 1 byte)	Handle command received over I ² C-bus.

4.4 Scatter loading description file

To support In-Application Programming, a scatter loading description file is used to specify the memory map of the image to the linker, in order to control the grouping and placement of the image components.

This is important, because the new image is placed at its intended location and not any other location that can corrupt the codes used to perform IAP.

4.4.1 Scatter loading description file for SBL

The SBL resides on the sector 0 of the slave MCU. It is divided into two regions: one for storing the firmware itself, the other is used to public the SBL API for User Application.

Table 2. Scatter loading description file for SBL (LPC17xx)

Load Region	Execution Region	Input Sections
0x00000000 - 0x00000FEF	0x00000000 – 0x00000FEF	Interrupt Vector Table, Code and RO data.
	0x10000000 – 0x10007BFF	RW data, ZI data.
	0x2007C000 – 0x20083FFF	RW data, ZI data.
0x00000FF0 - 0x00000FFF	0x00000FF0 - 0x00000FFF	SBL API.

Table 3. Scatter loading description file for SBL (LPC11xx)

Load Region	Execution Region	Input Sections
0x00000000 - 0x00000FEF	0x00000000 - 0x00000FEF	Interrupt Vector Table, Code and RO data.
	0x10000000 – 0x10001BFF	RW data, ZI data.
0x00000FF0 - 0x00000FFF	0x00000FF0 - 0x00000FFF	SBL API.

The last 1 kB of internal RAM, starting from 0x10007C00 for the LPC17xx and from 0x10001C00 for the LPC11xx, is used to store 1 kB of firmware data sent by the master MCU while upgrading firmware for the User Application.

4.4.2 Scatter loading description file for user application

The User Application resides in flash memory, from sector 1 to the last sector of the slave MCU. It is also divided into 2 regions; 1 for storing firmware data itself and the other for storing Firmware Version ID.

Table 4. Scatter loading description file for user application (LPC17xx)

Load Region	Execution Region	Input Sections
0x00001000 - 0x0007FFFB	0x00001000 – 0x0007FFFB	Interrupt Vector Table, Code and RO data.
	0x10000000 – 0x10007BFF	RW data, ZI data.
	0x2007C000 – 0x20083FFF	RW data, ZI data.
0x0007FFFC- 0x0007FFFF	0x0000FF0 - 0x0000FFF	Firmware Version ID

Table 5. Scatter loading description file for user application (LPC11xx)

Load Region	Execution Region	Input Sections
0x00001000 - 0x00007FFB	0x00000000 – 0x00007FFB	Interrupt Vector Table, Code and RO data.
	0x10000000 – 0x10001BFF	RW data, ZI data.
0x00007FFC- 0x00007FFF	0x00007FFC- 0x00007FFF	Firmware Version ID

The last 1 kB of internal RAM is also used to store 1 kB firmware data sent by master MCU while upgrading firmware for SBL.

5. How to run

This project is tested on Keil’s MCB1700 with LPC1768 version 1 and Keil’s MCB1000 with LPC1114. It requires two boards: one master and one slave.

5.1 Directory contents

The folder structure of the project is described in [Fig 16](#).



Fig 16. Project directory contents

In each example folder, there are four sub-folders:

- Folder “Keil”: includes Keil project file, scatter file and debug file. After compiling, output files would be placed in a sub-folder of this folder. The name of the sub-folder is the same to the name of selected target.
- Folder “drivers”: includes source code for controlling peripherals including I2C, UART, and GPIO.
- Folder “sbl”: includes SBL source code (Master/slave role).
- Folder “main”: includes main program.

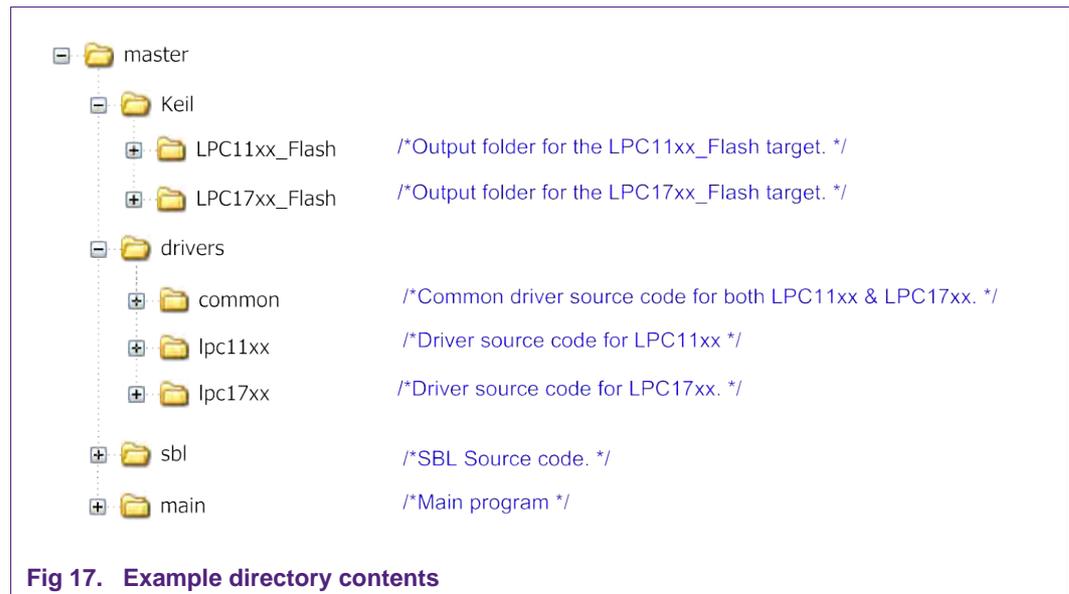


Fig 17. Example directory contents

5.2 Hardware configuration

5.2.1 MCB1700

These jumpers must be configured as:

- VDDIO: ON
- VDDREGS: ON
- Remaining jumpers: OFF

5.2.2 MCB1000

These jumpers must be configured as following:

- J2 – VDD: ON

5.2.3 I2C connection

I2C pins:

Function	MCB1700	MCB1000
SCL	P0.28	P0.4
SDA	P0.27	P0.5

Common ground must be connected together between two boards.

There must be a pull-up resistor on SDA and a pull-up resistor on SCL line. Refer to [Fig 2](#) "I2C Configuration" for more detail.

5.3 Software configuration

5.3.1 Tera Term setting

Serial display configuration

- 115200 bps
- 8 data bit
- No parity
- 1 stop bit
- No flow control

5.4 Steps to run

Step 1: Open SBL master project in **SBL\Examples\master** folder.

- Select the target relevant to the master board.
- Determine the size of User application firmware using SBL_FW_DATA_BLOCK_NUM macro in file "sbl.h".
- Build SBL master project.
- Burn hex file into master board. (If run on ROM mode)

Step 2: Open SBL slave Project in **SBL\Examples\slave** folder and User Application project in **SBL\Examples\user_app** folder.

- Select the target which relevant to the slave board.
- Build these projects.
- Erase all sectors on flash memory of slave board.

- Burn the hex file of SBL slave project into slave board.
- Burn the hex file of User Application project to master board.

Step 3: Connect UART0 on master board to COM port on your computer.

Step 4: Configure hardware, connect master board and slave board as mentioned in section 5.2.

Step 5: Configure serial display as mentioned in section 5.3.

Step 6: Reset slave board. The LED at P2.2 is lighted on to notify that the system is in SBL mode.

Step 7: Reset the master board. The welcome message is shown.



Fig 18. Terminal output when master board resets

- Press 'r' to read the user application firmware version ID from slave. If this is the first time upgrading firmware, 0xFF will be displayed for all version details.
- Press 'u' to start upgrading slave firmware. The master gets firmware data from sector 1 of its flash memory, and then sends to the slave. The firmware data size is determined by the SBL_FW_DATA_BLOCK_NUM macro.

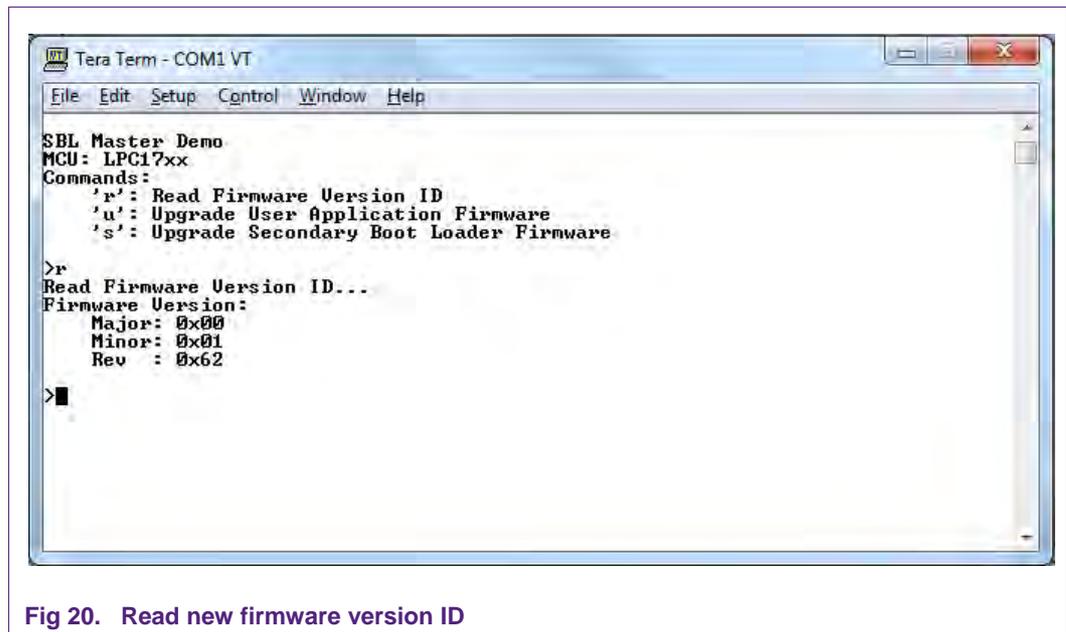


Fig 20. Read new firmware version ID

- To upgrade SBL firmware:
 - First, download the binary firmware file from the SBL slave project (stored in the path **SBL\Examples\slave\Keil\<Target Name>**) to sector 1 of flash memory in master MCU:
 - Open SBL slave Project.
 - Open Target Option Dialog, select Utilities Tab.
 - Choose External Tool for Flash Programming as below.

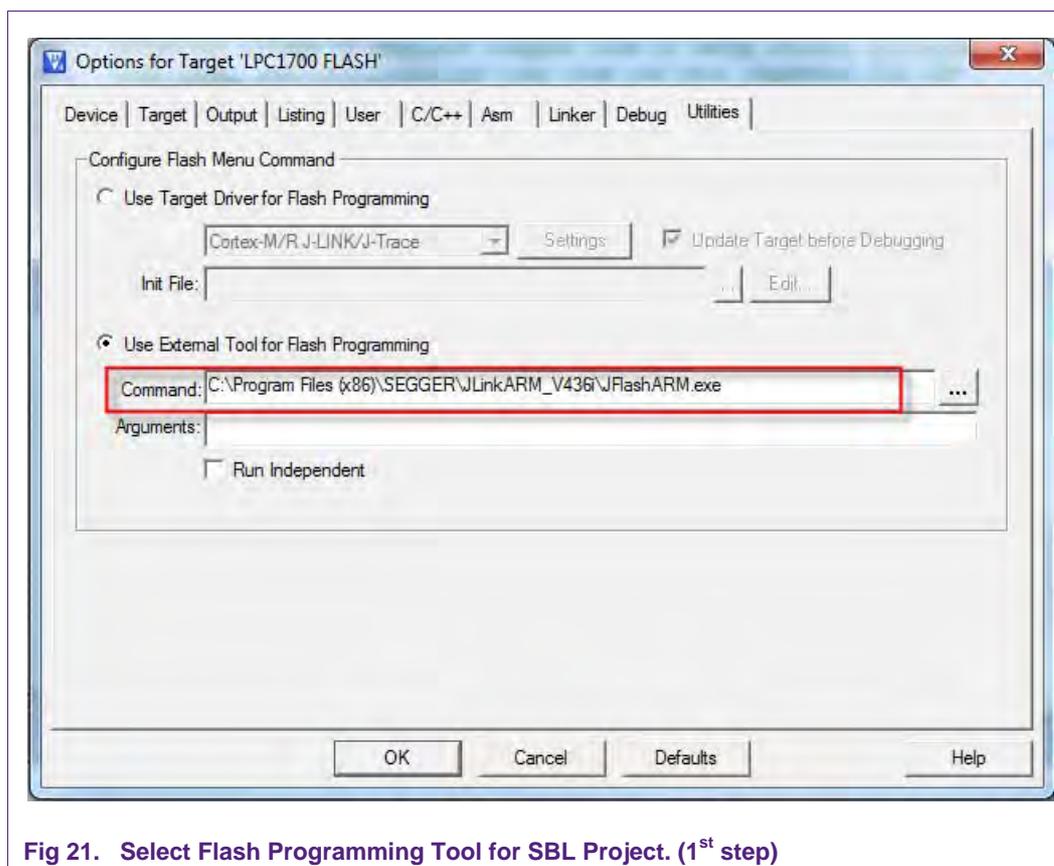


Fig 21. Select Flash Programming Tool for SBL Project. (1st step)

- Select Flash→ Download. The J-Flash ARM Application is opened.
- Select File→ Open Project; browse to file “LPC1768.jflash” if the master is LPC17xx MCU. If it is LPC11xx MCU, please select “LPC1114.jflash”.

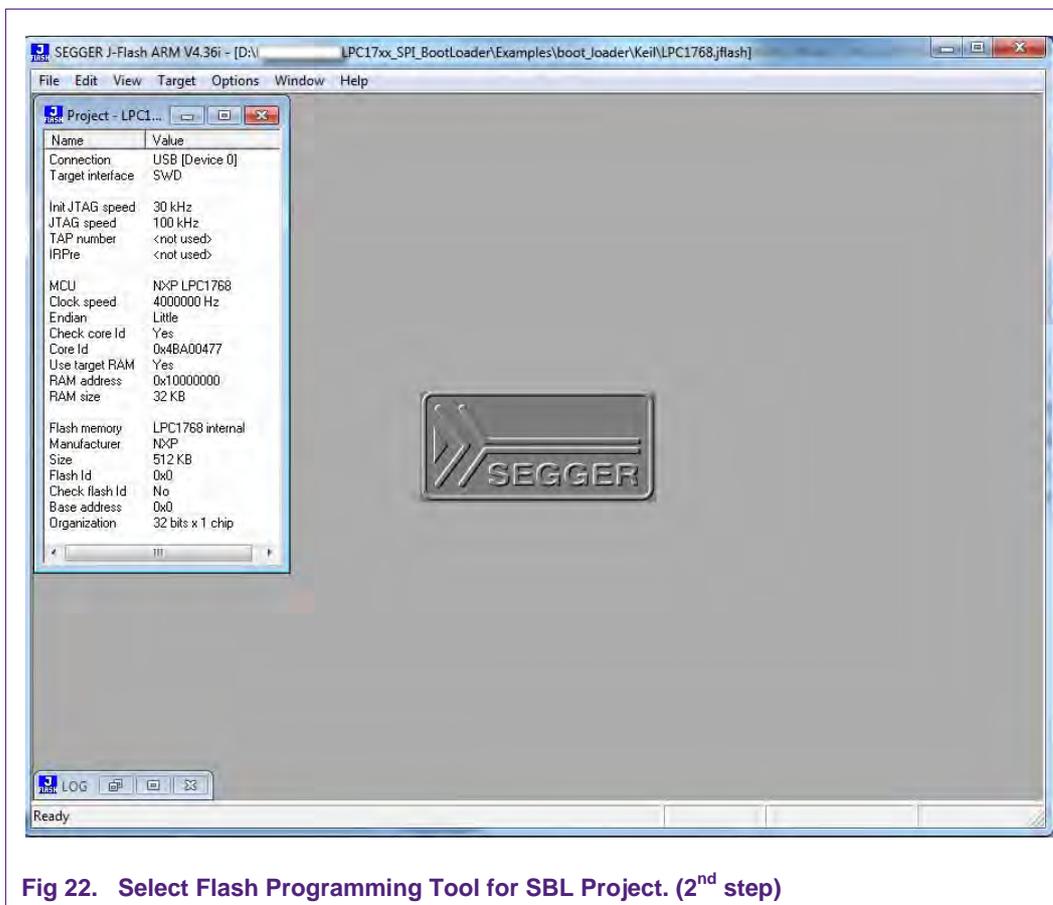


Fig 22. Select Flash Programming Tool for SBL Project. (2nd step)

- Select File→Open data file, browse to sbl.bin file in the relevant output folder of SBL Project. Set the Start Address as 0x1000.

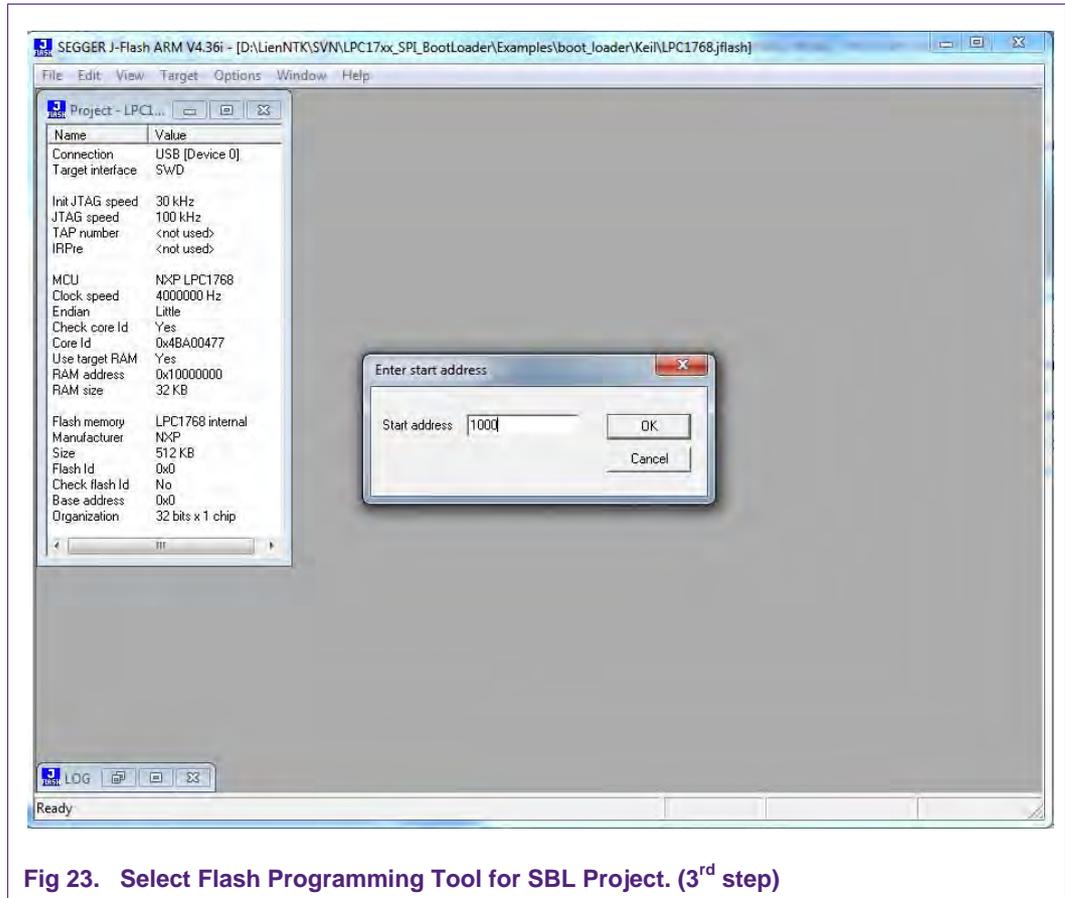


Fig 23. Select Flash Programming Tool for SBL Project. (3rd step)

- Select Target→Program to program the master board.
- Reset the master board.
- Press 's' to upgrade firmware for SBL.

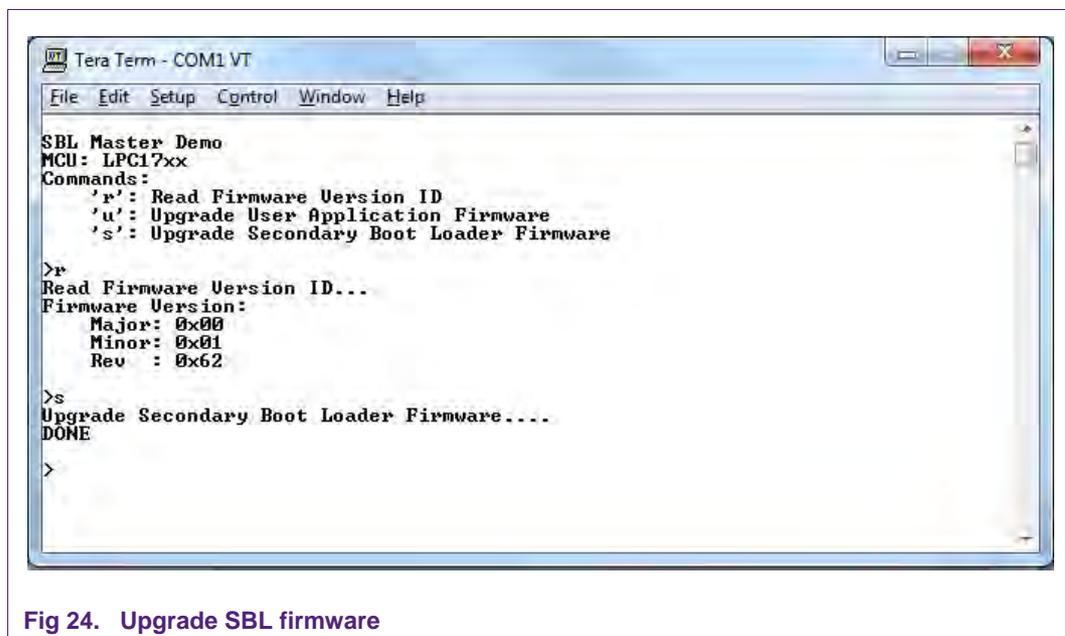


Fig 24. Upgrade SBL firmware

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